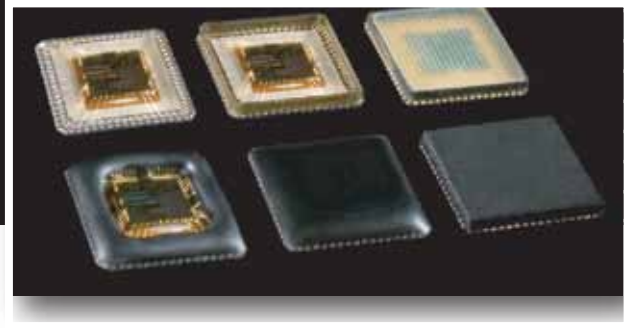


## ENCAPSULATION OPTIONS



### Advantages:

- Choose the encapsulation style that meets your prototyping needs
- Mix & match multiple encapsulation options on the same assembly order
- Assembly turn times from 8 hours to 3 days available

**Flattened/Remolded** (fully encapsulated with filled epoxy utilizing Quik-Pak proprietary molding process)

- Test socket compatible/meets JEDEC mechanical standards
- Suitable for customer samples, pre-production runs, etc.
- Auto handling compliant
- Electrical performance equivalent to production package
- Optional marking / branding service available

**Glob Top** (fully encapsulated with filled epoxy – domed top surface)

- Electrical performance equivalent to production package
- Optional marking/branding service available
- Suitable for chip-on-board applications

**Partial Open Cavity** (encapsulated with filled epoxy in selected areas)

- FIB ready, uV erasable
- Ideal for circuit repair, visual inspection, emission studies, etc.
- Wires partially protected from mechanical damage

**Open Cavity with Frame or Lid** (no encapsulant, custom frame and/or lid)

- Die & wires protected, yet accessible
- Ease of probing die & chip
- Test socket compatible
- FIB ready, uV erasable
- Ideal for circuit repair, visual inspection, emission studies, etc.
- Suitable for MEMS applications

**Open Cavity** (wire bonded chip with no encapsulant, die is exposed)

- Ease of probing die & chip
- FIB ready, uV erasable
- Ideal for circuit repair, visual inspection, emission studies, etc.

**Clear Encapsulant** (encapsulated with non-filled epoxy)

- Easy wire bonding verification
- Visual sample of assembled product
- Eliminates need for X-Ray wire length measurements
- Lower dielectric constant
- Suitable for IR or visual light transmission applications

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